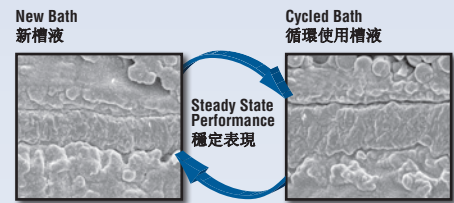
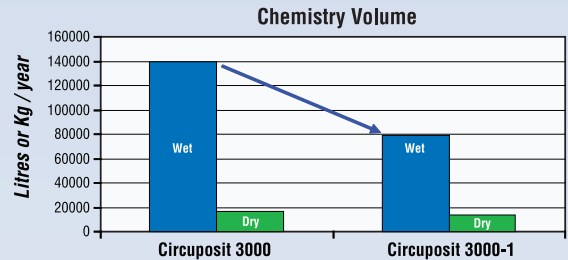


Universal Electroless Copper | 化學沈銅工藝

CIRCUPOSIT™ 3350-1 Electroless Copper

Features and Benefits 特性及優點

- A universal electroless copper process
可被廣泛應用之化學銅製程
- Reduce chemistry volumes
減少藥液使用量
- Reduce catalyst strength
減少催化劑藥液強度
- Increased thermal cycle reliability
增進熱沖擊下之信賴性
- Steady state operation
槽液操作穩定
- Designed for today's materials
適用於現今之先進材料
- Exceptional performance and reliability
具有卓越的產品表現及信賴性
- Global reference list
客戶遍及全球



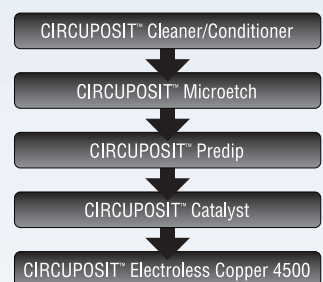
Horizontal Desmear / PTH | 水平化銅工藝

CIRCUPOSIT™ 4000 Horizontal Desmear / PTH

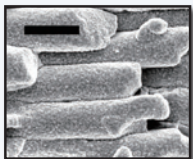
Advantages 優點

- Capable of conveying thin boards (thickness: 50 µm)
能夠薄板(厚度: 50 µm)連續生產
- No need of racking
不需要框架
- Capable of conveying FPC boards by reel-to-reel
軟板能夠卷對卷連續生產
- High productivity due to shortened processing time
較短的反應時間可以提高產量
- Improvement of working environment by closed system
密閉式反應改善工作環境
- Applicable to various resins such as FR-4, High Tg, and polyimide
可應用於不同的樹脂材, 如 FR-4, High Tg, and polyimide

Process 製程



Characterization 特性描述



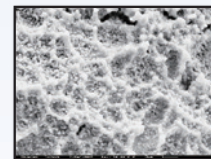
Excellent glass coverage and ultra fine grain structure
優異的玻璃覆蓋能力及細緻的沈積



Ultimate in PTH reliability
內層優異的化銅信賴性



Excellent coverage in microvia
深埋孔優異的覆蓋能力



Conventional 傳統化銅



C-4000

Electroless Copper Deposit:
C-4000 provides fine grain deposits
化銅沈積: C-4000的沈積較細致